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Application No. 09/590,406

Whitaker Docket No. 17541

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **William Palmteer**

Application No.: **09/590,406**

Examiner: **Quynh-Nhu H. Vu**

Filing Date: **June 8, 2000**

Group Art: **2841**

Title: **SOLDER-COATED ARTICLE USEFUL FOR SUBSTRATE ATTACHMENT**

CERTIFICATE OF MAILING

I hereby certify that this correspondence, along with any papers indicated as being enclosed, are being deposited as First Class Mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on February 4, 2003.

2-4-03
Date

Kathryn M. Lynn
Kathryn M. Lynn

Commissioner for Patents
Washington, DC 20231

AMENDMENT

Sir:

Responsive to the second Office Action dated November 6, 2002, Applicant amends the application as noted below and respectfully requests favorable reconsideration of this application.

In the Claims

Please amend the claims as noted below.

1. (Twice Amended) A solder-coated article comprising:
a substantially non-deformable dielectric core having a largest dimension ranging from 1 to 1000 microns;